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Full Material Declaration for attached parts list

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Diotec Semiconductor

Diotec Semiconductor AG

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Declarations authorised by
Udo Steinebrunner, Product Manager, -

Declaration effective from: 02 January 2014 [Approved: 01 October 2024 07:11 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	**Material Group**	**Max mass %**	**Substance**	**CAS Number**	**Max mass %**
Chip (die)	Other inorganic materials	0.46%	Silicon	7440-21-3	100%
Die attach	Other nonferrous metals	0.91%	Oxirane, [[4-(1,1-dimethylethyl)phenoxy]methyl]-	3101-60-8	1%
			Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	15%
			SILVER, ELEMENTAL	7440-22-4	84%
Encapsulation	EP (Epoxy resin)	48.91%	Aluminum oxide trihydrate	21645-51-2	0.1%
			Carbon black	1333-86-4	0.5%
			resin	9003-35-4	5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	10%
			Quartz silica	14808-60-7	84.4%
Inner preparation	Gold	0.04%	GOLD, ELEMENTAL	7440-57-5	100%
Leadfinish	Tin plating	5.5%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	44.18%	Phosphorus	7723-14-0	0.03%
			IRON, ELEMENTAL	7439-89-6	0.27%
			SILVER, ELEMENTAL	7440-22-4	2.7%
			COPPER, ELEMENTAL	7440-50-8	97%

Attached parts list

Part number	Part name
SOT-26/SOT-457-HF Au	Diode / Transistor SMD